

Silver and Sulfur: Case Studies, Physics, and Possible Solutions

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Introduction

- Silver is a common metal in electronics
 - Along with gold, copper, and solder
- Tendency to migrate
 - Driven by oxidation behavior in presence of moisture + bias
- Industry response
 - Additional test requirements
 - Alloying with noble metals (Ag + Pd)
- Concerns with sulfidation a more recent phenomenon



Silver Sulfidation

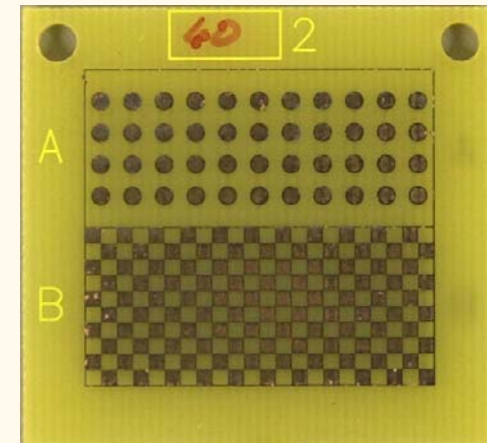
- Also known as sulfuration
 - Well known in museum and conservation studies
- Initiates through the reduction of hydrogen sulfide (H_2S) or carbonyl sulfide (COS) to HS^-
- Two potential subsequent reactions in an aqueous solution
 - HS^- can react directly with silver ions that have oxidized
 - HS^- can adsorb to the surface, reacting to form a sulfide salt
- Presence of oxidizing species (i.e., Cl) can increase corrosion rate
- Principal product of HS^- and silver is silver sulfide (Ag_2S)
 - Also known as acanthite (monoclinic)

Case Studies

- Classic problem-solving approach in business education
- Four case studies of sulfidation of silver
 - Corrosion Behavior and Mixed Flowing Gas (MFG)
 - Sulfur Attack of Silicone Encapsulated Hybrid Circuit
 - Elevated Resistance of Surface Mount Resistors
 - Creepage Corrosion on Immersion Silver Plated PCBs
- Provides a path for discussion of physics of this mechanism
 - Initial reaction, influence of environment, etc.

Corrosion Behavior and MFG

- Corrosion coupon plated with immersion silver
 - ❑ No solder mask
 - ❑ Two arrays
- Preconditioning
 - ❑ 2X Reflow
 - ❑ 1X Wave
- 30 coupons
 - ❑ Up to 10 days exposure

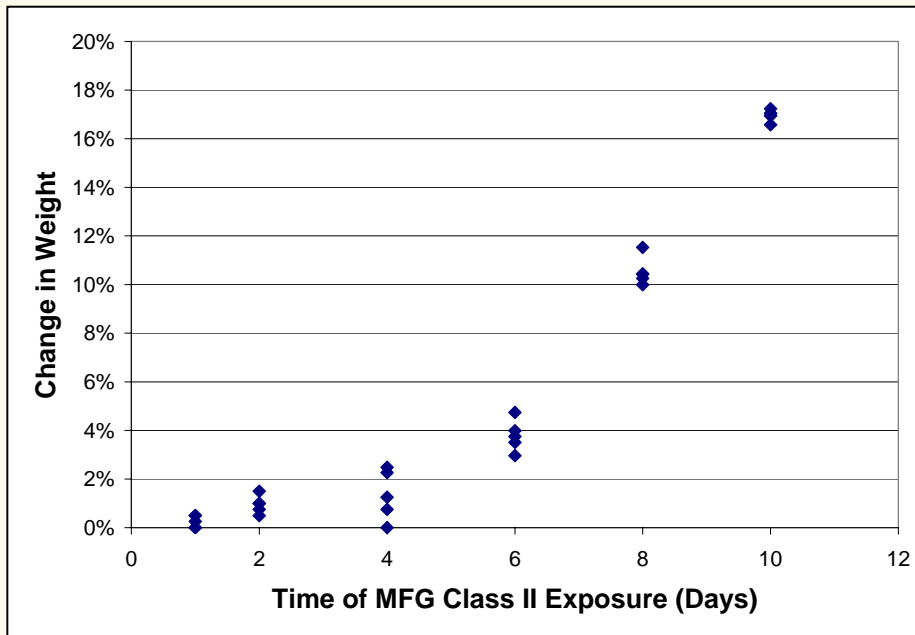


Class	RH (%)	Temp (°C)	H ₂ S (ppb)	Cl ₂ (ppb)	NO ₂ (ppb)	SO ₂ (ppb)
I	----	----	----	----	----	----
II	70±2	30±2	10±5	10±3	200±50	----
IIA	70±2	30±1	10±5	10±3	200±50	100±20
III	75±2	30±2	100±20	20±5	200±50	----
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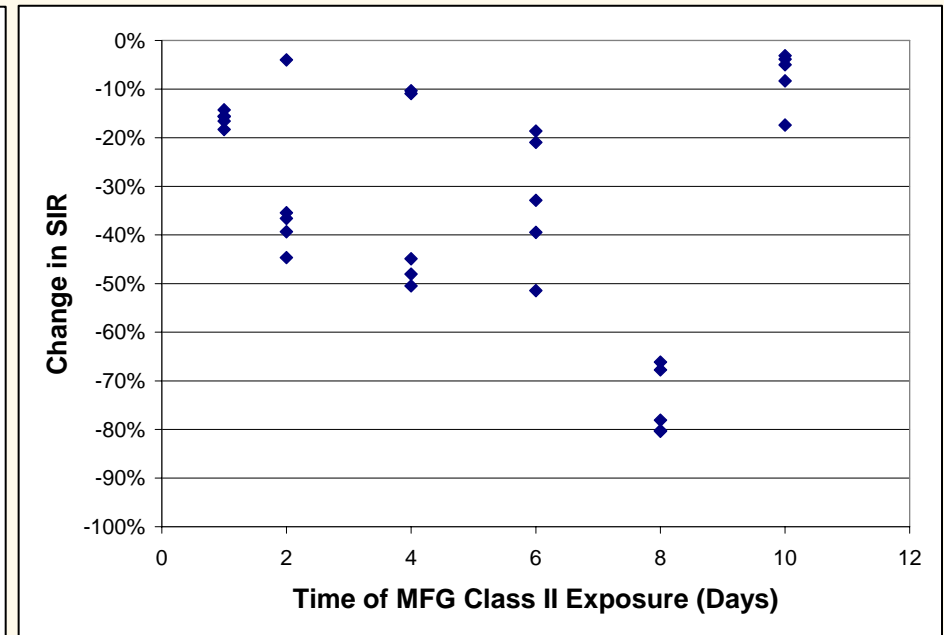
Gas concentrations for EIA MFG standards. IIA was used for the solderability testing

Results

Weight Gain



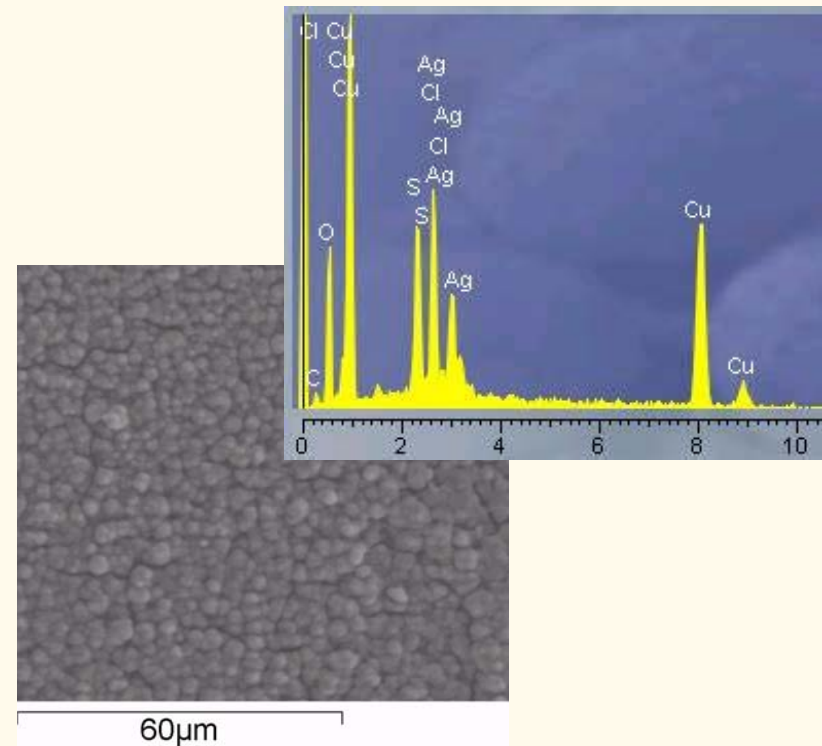
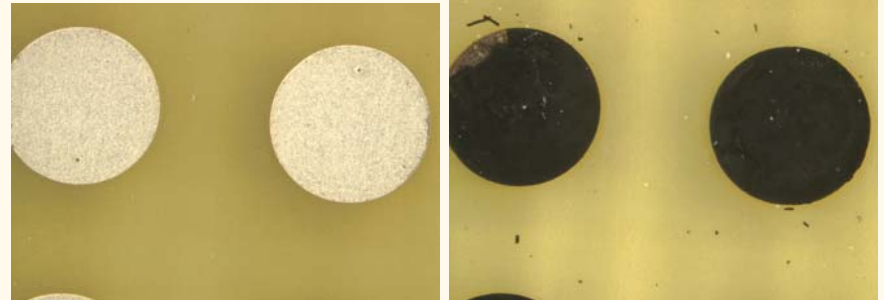
Change in Surface Insulation Resistance (SIR)



- Weight gain provides strong evidence of chemical reaction
 - 3X weight gain compared to SnPb HASL coupons
- Change in SIR likely due to moisture absorption
 - Absolute SIR still above 1×10^{12} ohms

Results (cont.)

- Strong black color change after exposure
 - Consistent with sulfidation
 - Ag_2S is black
- Detection of chloride and sulfide
 - Could suggest presence of AgCl
- AgCl is white, but exposure to light can cause disassociation into chlorine and silver
 - Metallic silver is gray-black
- Note: No migration products

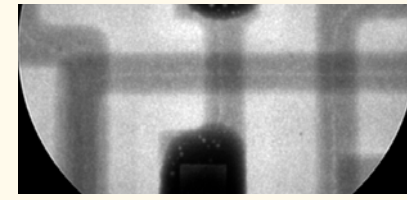
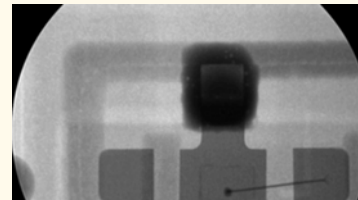
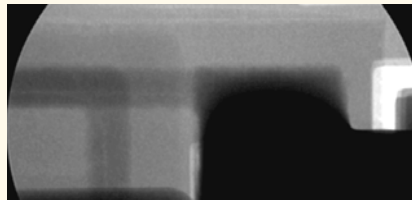


Sulfur Attack of Encapsulated Hybrid

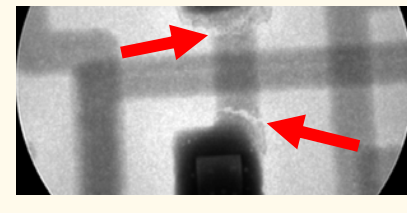
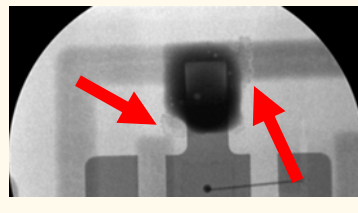
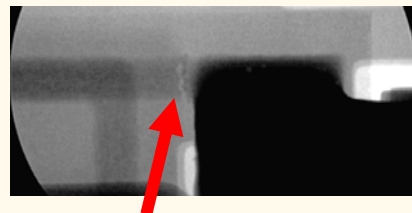
- Silicone encapsulant, ceramic hybrid
- Used in industrial controls
- Customer reported failures after 12 to 36 months in the field
- X-ray identified several separations



'Good' hybrid



'Bad' hybrid



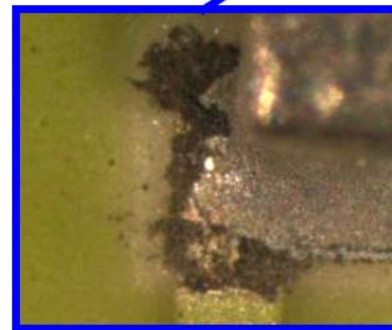
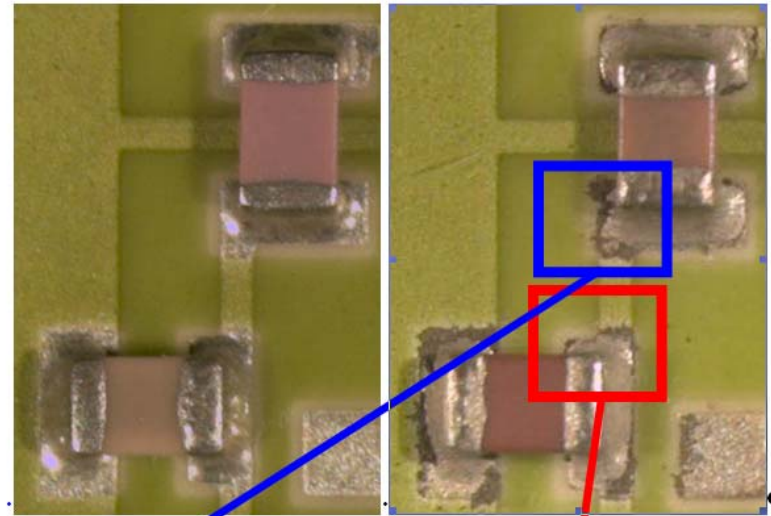
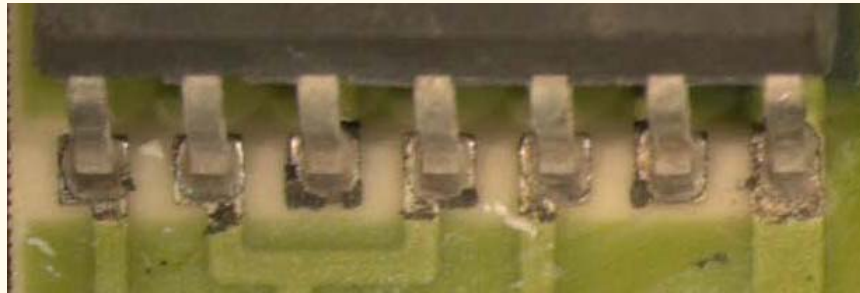
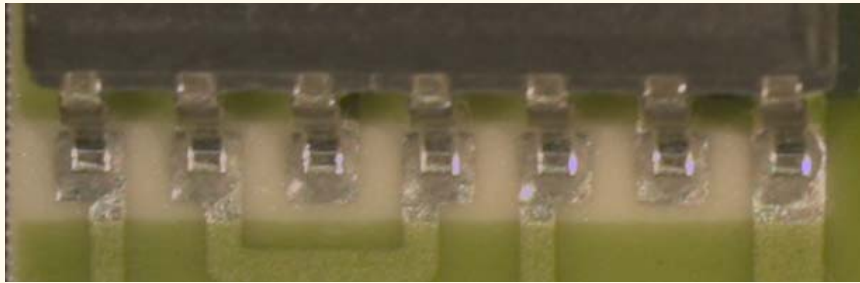
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Encapsulated Hybrid (cont.)

- Silicone encapsulant was removed using Dynasol
- Visual inspection revealed black corrosion product throughout the hybrid
 - Most severe in areas with no solder or solder mask covering silver thick film traces
 - Attack through the solder mask in some locations

Sulfur Corrosion Sites

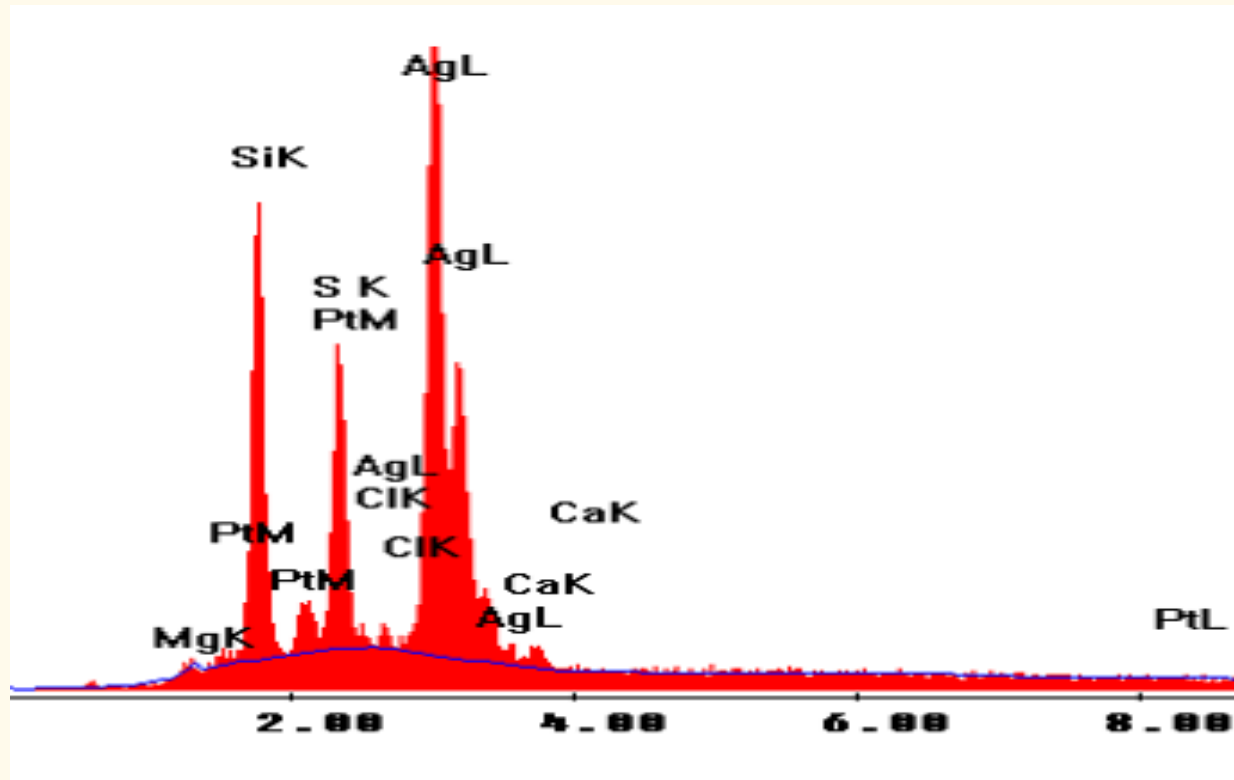


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Elemental Analysis



- Sulfur and silver peaks detected
- Note: No migration products were observed

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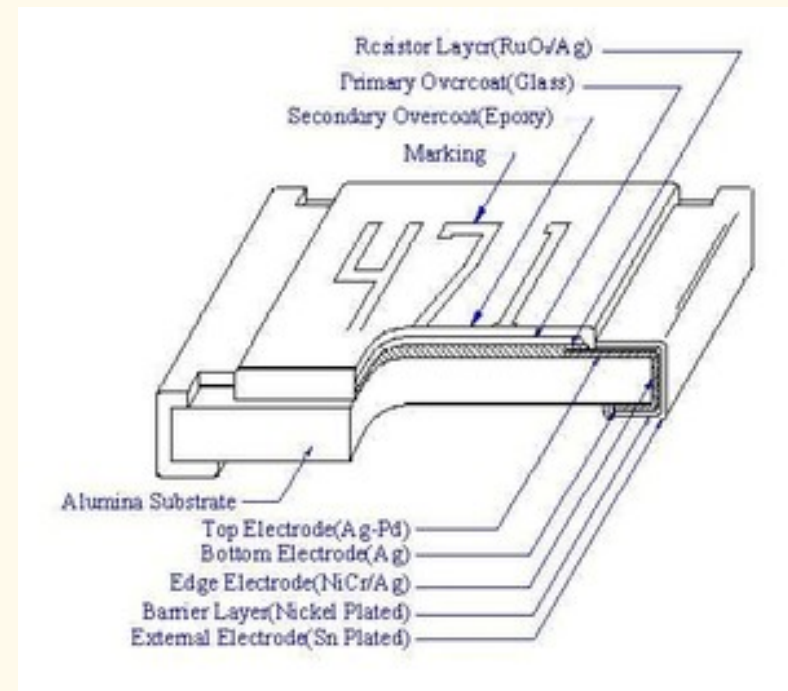
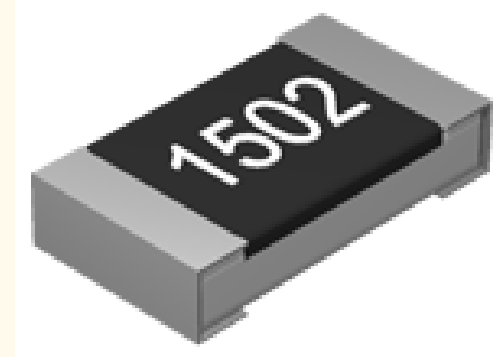
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Corrective Actions

- Manufacturer added a silicone coating under the silicone potting
 - Will this help?
- Possibly
 - Corrosion primarily occurred in areas where silver thick film traces were exposed
 - Additional coating should slow the reaction sufficiently to provide desired lifetime
- Silicone potting was not successful in preventing sulfidation
 - Silicone coating will have the same open structure (porous)
 - Could allow penetration of corrosive gases (e.g., H₂S)

Elevated Resistance of SMT Resistors

- Several field issues reported in thick film resistors
 - Use silver as the base conductor (cost, stability, oxide resistance, compatibility with ruthenium oxide)
- Failures reported in environments with high levels of sulfur-based gases
 - E.g., hydrogen sulfide (H₂S), sulfur dioxide (SO₂), and carbonyl sulfide (COS),
 - Failure mode is increasing resistance (electrical open)

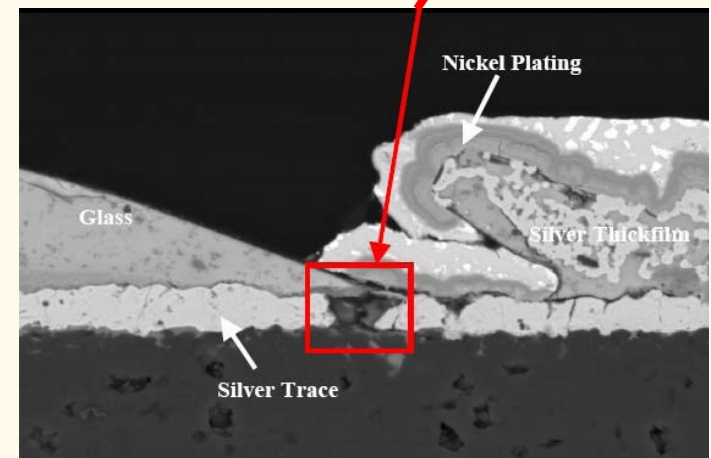
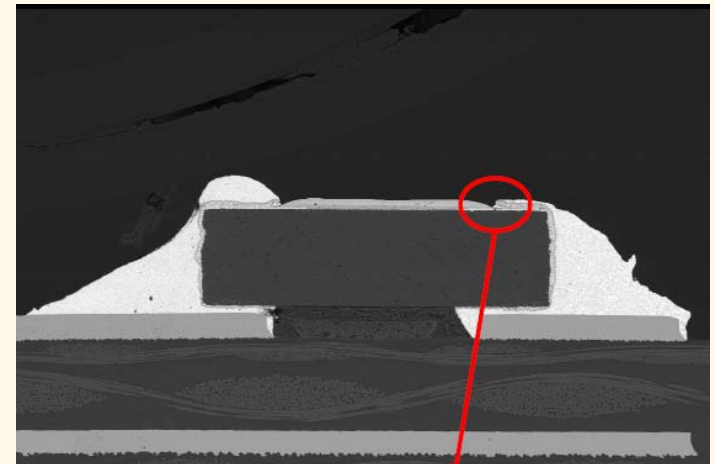


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SMT Resistors (cont.)

- Sulfur attack of silver occurs at the abutment of the glass passivation layer and the resistor termination
 - ❑ Cracks or openings can allow the ingress of corrosive gases,
 - ❑ Reaction with the silver to form silver sulfide (Ag_2S)
- Large change in resistance
 - ❑ $\rho_{\text{Ag}} = 10^{-8} \text{ ohm-m}$;
 - ❑ $\rho_{\text{Ag}_2\text{S}} = 10 \text{ ohm-m}$
 - ❑ Up 20K ohms (0.01 x 0.01 x 0.5mm)
- Manufacturers' solutions
 - ❑ Sulfur tolerant – silver alloys
 - ❑ Sulfur resistant – silver replacement

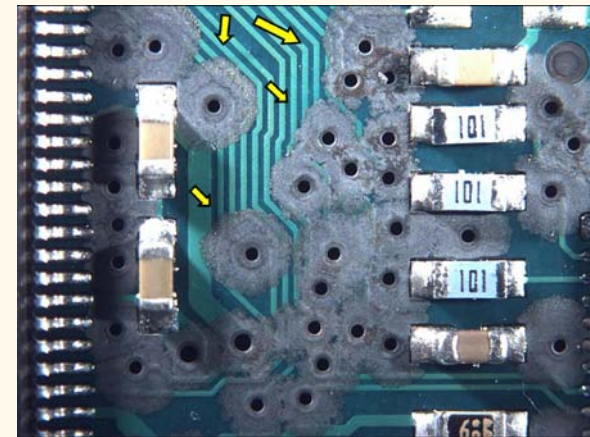
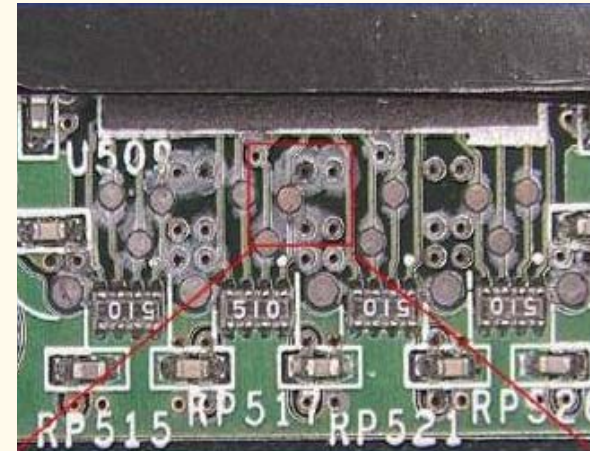


SMT Resistors (Observations)

- This mode of sulfur corrosion displayed two interesting behaviors.
- First: Extended time to failure (1 - 4 years)
- Second: Observation that a majority of failures occurred in assemblies that were encapsulated in silicone
 - Silicone structure could act as a 'sponge' for sulfur-based gases.
 - Behavior is not uncommon for gases and polymeric compounds; observed with water molecules and epoxy resins
- In epoxies, water can exist in two forms (bound and unbound)
 - Bound molecules are attracted to the polymer chains through hydrogen bonding and become immobilized.
- If 'bounding' exists with H₂S or SO₂ and silicone, it may provide the gases time to react with the silver conductor
 - Alternate theory: Presence of moisture and H₂S / SO₂ in silicone create aggressive chemistry

Corrosion of Immersion Silver

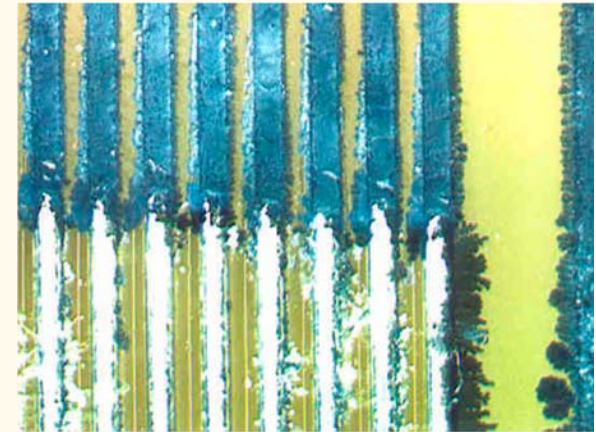
- Recent field issues with printed circuit boards (PCBs) plated with immersion silver
 - Sulfur-based creepage corrosion
- Failures in customer locations with elevated levels of sulfur-based gases
 - Rubber manufacturing
 - Sewage/waste-water treatment plants
 - Vehicle exhaust fumes (exit / entrance ramps)
 - Petroleum refineries
 - Coal-generation power plants
 - Paper mills
 - Landfills
 - Large-scale farms
 - Automotive modeling studios
 - Swamps



P. Mazurkiewicz , ISTFA 2006

Case Study Discussion (Creepage Corrosion)

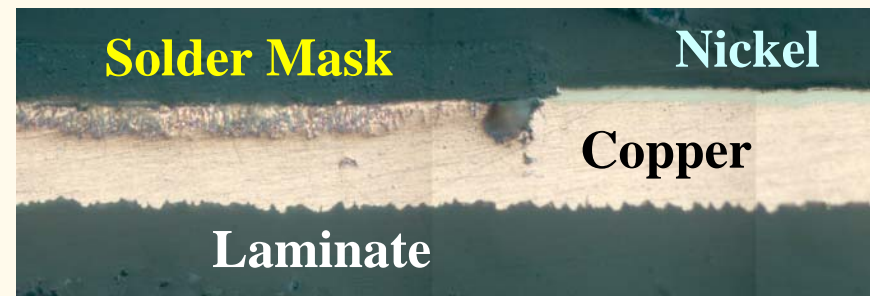
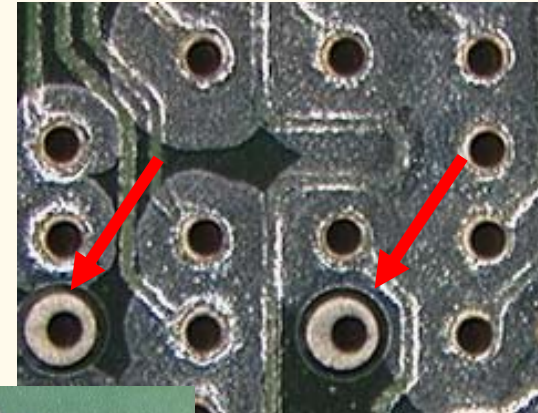
- Creepage in field
- No creepage under Class II MFG
- Creepage under Class III?
 - Sometimes (Veale; Hillman)
- Strong indication that creepage mechanism requires that one or more MFG test parameters are exceeded
 - Especially %RH
 - Hillman: >75%RH
 - Cullen: 93%RH
- How must MFG be modified to replicate field issues?



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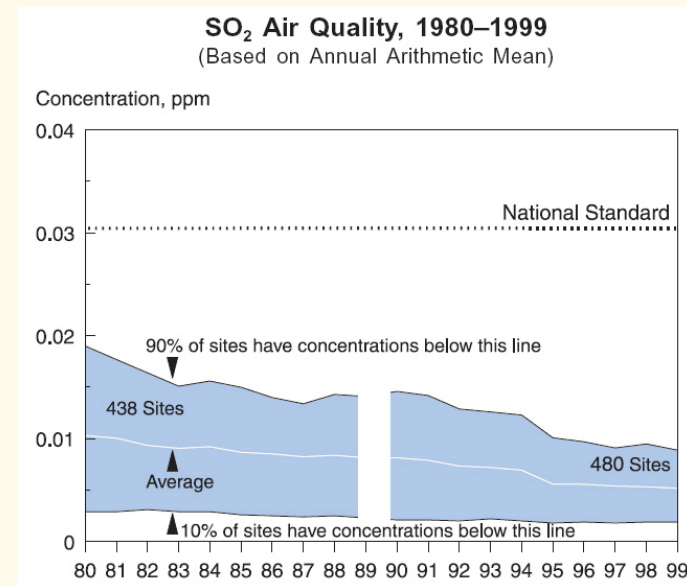
MFG Test Structures

- Influence of solder mask
 - ❑ Field: Creepage primarily on solder mask defined (SMD) pads
 - ❑ Test: Delay in creepage on non-solder mask defined pads (NSMD)
- Similar mechanism observed with electroless nickel / immersion gold (ENIG) plating
 - ❑ Corrosion of copper trace at solder mask edge
- Potential mechanisms
 - ❑ Solder mask absorption of sulfur-based gases
 - ❑ Crevice corrosion (depletion of oxygen)
 - ❑ Entrapment of flux residues



MFG Test Conditions

- Are existing MFG test conditions still relevant?
 - ❑ Different material system (silver, not copper)
 - ❑ Changing environment (is there more / less pollution?)



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MFG Test Conditions (Sulfur-Based Gases)

SO2

- MFG Test
 - 100ppb, 200ppb
- Average annual outdoor
 - 2-20ppb (USA)
 - 25-100ppb (Asia)
- 24 hour
 - ~150ppb (NAAQS / Telcordia)
 - 150-600ppb (Industrial-USA)
 - 100-1500ppb (Asia)
- May not be critical for sulfidation of silver
 - Rate independent of SO2 concentration

H2S

- MFG Test
 - 10ppb, 100ppb, 200ppb
- Average annual outdoor/indoor
 - 0.05 to 0.8ppb
- 24 hour (outdoors)
 - 8 to 100ppb (State Regs)
- 24 hour (indoors)
 - 500 to 20,000 ppb
- May be more critical

	Clean room	Controlled environment	Rural	Urban with heavy traffic or industrial	Adjacent to industrial	Inside industrial
SO2	100 ug/m ³ 38 ppb	100 38	100 38	1000 380	10000 3800	40000 15300
H2S	1.5 0.6	10 4	10 4	500 200	10000 4075	70000 28500

Test Conditions (cont.)

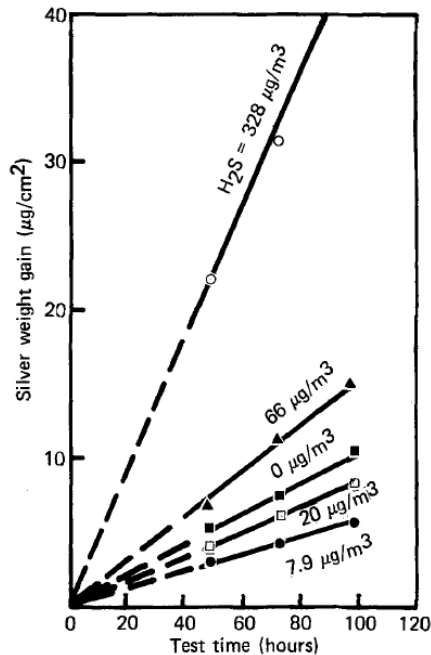
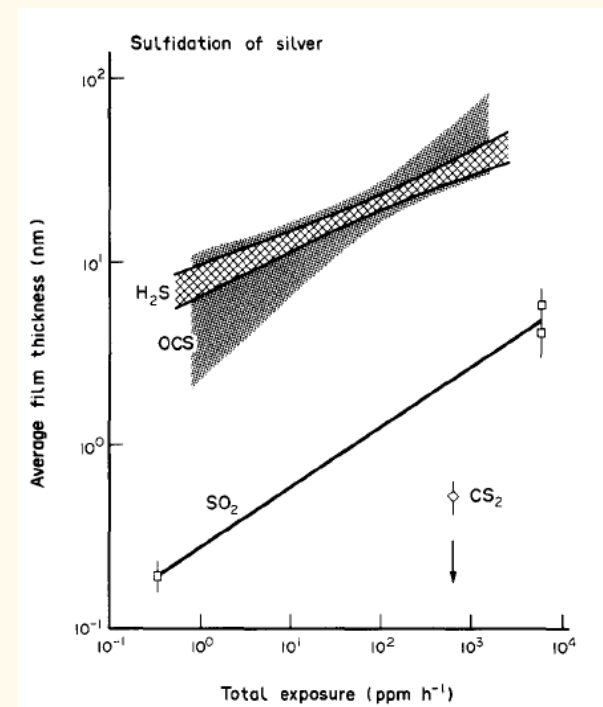


Fig. 6. Weight gain of silver vs. test time for various H₂S concentrations in environment A (Table III).

Carbonyl Sulfide (COS)

- Ignored by MFG
- Outdoor levels can be higher than H₂S
 - Nominal: 0.5 – 0.8ppb
 - Elevated: 80 ppb
- Can be as corrosive as H₂S



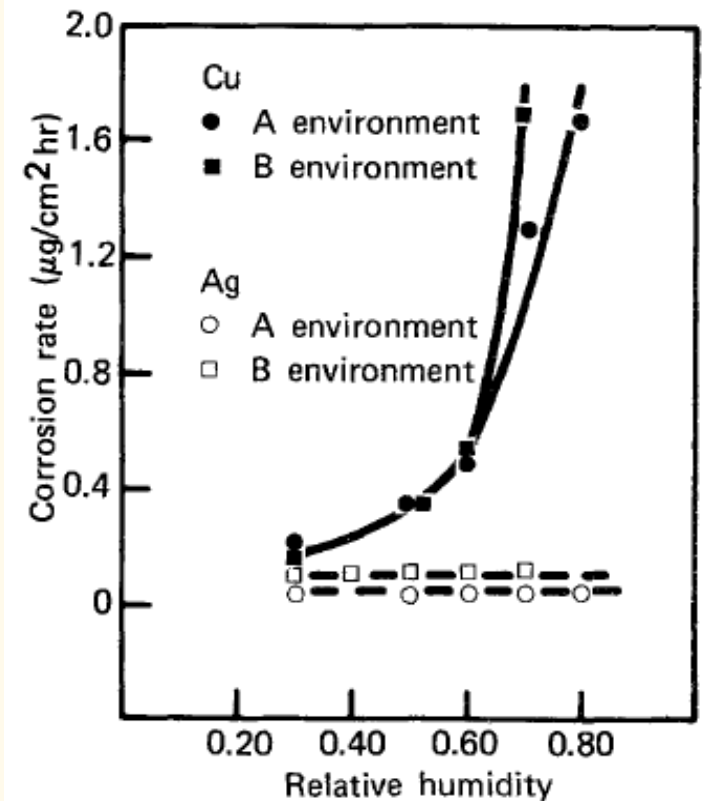
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Test Conditions (Relative Humidity)

- Influence of %RH somewhat contradictory
- Vernon reported a critical %RH (70-80%)
- Graedel reported an increasing corrosion rate with increasing %RH
 - Driven by monolayers (ml) of moisture
 - $\ln(ml) = 2.73 \text{ p/p}_0 - 0.366$
 - (p/p₀ is %RH)
- Rice reported no influence of %RH

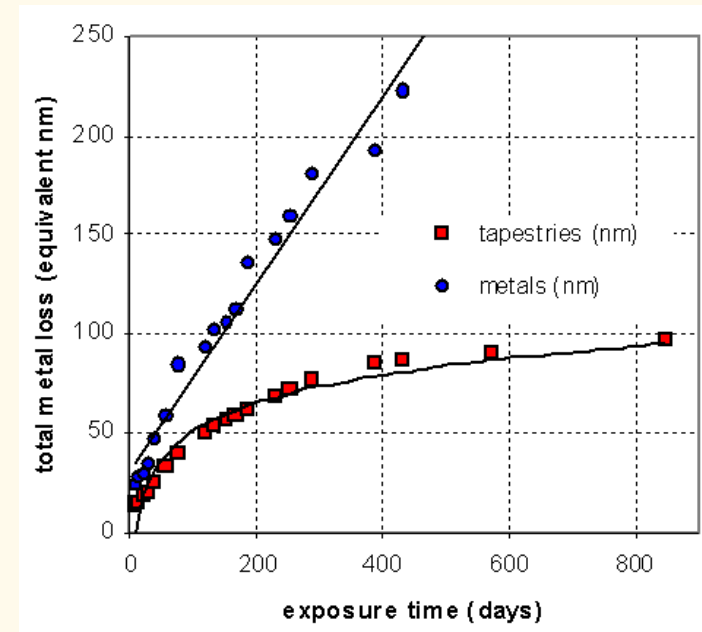


Relative Humidity

- Validation of Rice's observation
 - %RH levels in ceramic hybrid and thick film resistors coated with hydrophobic silicone likely low
- Important differentiation by mechanism
 - Most references investigate the tarnish aspect of sulfidation
 - Creepage behavior is likely very sensitive to %RH
- The rough surface of a polymeric material becomes conducive to material transport once micro-condensation within occurs.
 - 'Filling-in' of surface pores may greatly reduce the adhesion of the polymer surface
 - Allows forces created by volumetric expansion of corrosion product to 'push' the growth out to an adjacent conductor

Discussion

- Modification of MFG test specs may be appropriate
 - Elimination of SO₂ gases
 - Increase in H₂S concentrations (>200 ppb)
 - Possible intro of COS
 - Elimination or reduction of Cl₂
- Speculation that formation of AgCl inhibits sulfidation of silver
 - Elevated Cl₂ displays parabolic behavior
 - Elevated H₂S displays unlimited growth



Conclusion (Questions to Ask)

- What is the interdependence of %RH, and sulfur gas concentration in regards to the preponderance for creepage corrosion? E.g., does a higher %RH allow for a lower critical H₂S concentration?
- What are the influence of surface contaminants (hygroscopic, sources of chlorine, various acids) in terms of concentration and activity?
- Why were the organic inhibitors added to immersion silver to resist tarnishing unable to prevent creepage corrosion?
- Is there a critical sulfur-based gas concentration limit, below which these reactions will not occur?
- Would this critical gas concentration vary as a function of other gases, temperature, or relative humidity?
- What is the role of silicone potting compounds and epoxy solder mask on sulfidation and creepage corrosion?
- What is the potential role of board design and manufacturing processes?
- Is there a test to identify if this is a problem for my products?
- How can this mechanism be prevented in future products with exposed silver metal?

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*Best Regards,
Dr. Craig Hillman, CEO*

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